Anna Tauke-Pedretti

Program Manager, DARPA/MTO

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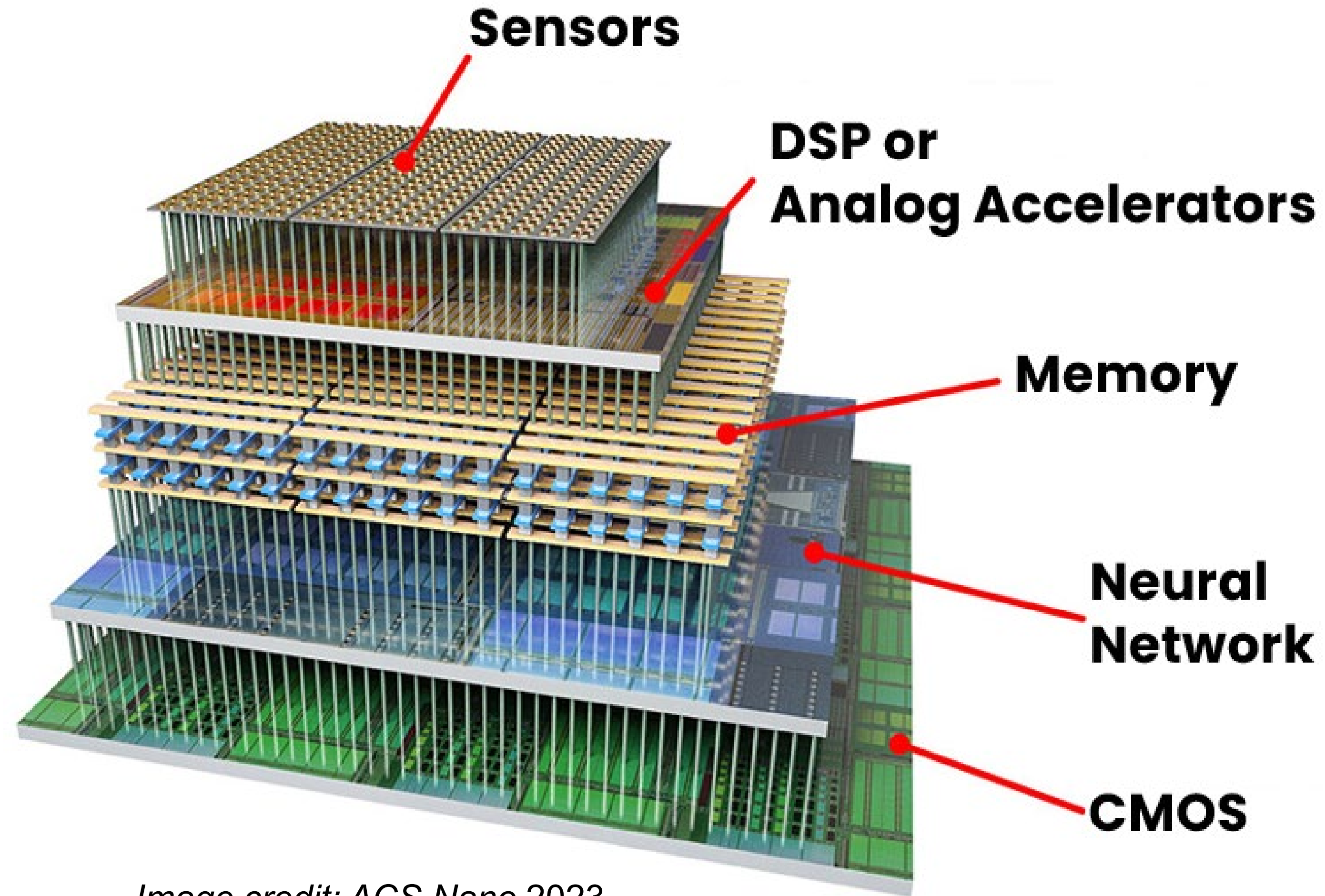
3DHI TECHNOLOGY

EXPANDING THE PEFORMANCE ENVELOPE

- Failure analysis
- Thermal management
- Data transmission



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INFRASTRUCTURE

DOMESTIC PLATFORM

- Sustainable ecosystem development
- Manufacturing challenges for 3DHI microsystems
- Chip compatibility for integration

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New Applications Enabled by Complex 3D Microsystems

Joshua Fryman, *Intel Corporation*

Panel: 3DHI Ecosystem

Mark Horowitz, *Stanford University*
Bill Phillips, *Northrop Grumman*
Philip Wong, *Stanford University*

3DHI Challenges and Solutions

Justin Ford, *Sandia National Laboratories*
Muhannad Bakir, *Georgia Institute of Technology*
Keren Bergman, *Columbia University*

NGMM Review

Carl McCants, *DARPA*

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